ABSTRACT

INTEGRATED CIRCUIT PACKAGE WITH LEADFRAME LOCKED ENCAPSULATION AND METHOD OF MANUFACTURE THEREFOR

A semiconductor including a leadframe having a die attach paddle and a number of leads is provided. The die attach paddle has a recess to provide a number of mold dams around the periphery of the die attach paddle. An integrated circuit is positioned in the recess. Electrical connections between the integrated circuit and the number of leads are made, and an encapsulant is formed over the integrated circuit and around the number of mold dams. (Fig. 5)